# Final Product/Process Change Notification 202207008F01

**Issue Date**: 29/07/2022

Effective Date:29/10/2022

Here is your personalized quality information concerning products our customers and partners purchased from Ampleon.

# Management Summary

In order to become disentangled from NXP fabs, Ampleon will transfer its current NXP production locations to non-NXP production locations.  Change Category			
[] Wafer Fab process	[] Assembly Process	[] Product Marking	[] Design
[] Wafer Fab materials	[] Assembly Materials	[] Electrical spec./Test coverage	[] Mechanical Specification
[X] Wafer Fab location	[] Assembly Location	[] Test Location	[] Packing/Shipping/Labeling

### Transfer of LDMOS die in the BLC9G21LS-60AV and BLC2425M9LS250

### **Information Notification**

For this product the LDMOS die will transfer from ICN8 to VIS. See presentation in ePCN tool

# Why do we implement this change?

To transfer our production locations to non-NXP fabs and for the short term to strengthen our supply chain with a 2nd source.

### **Identification of affected Products**

Product identification does not change

### **Product availability**

Sample information

Samples are available upon request

### Production

Planned first shipment

29/10/2022

### **Impact**

**Data Sheet Revision** 

No impact to existing datasheet

### **Disposition of Old Products**

Existing inventory will be shipped until depleted.

# **Timing and Logistics**

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 2022-08-28.

# **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact Ampleon "Quality Support Team".

For all Quality Notification content inquiries, please contact your local Ampleon Sales Support team.

At Ampleon we are dedicated to creating optimal value for our customers.

Ampleon Quality Management Team.

12NC Partnumber

934960054517 BLC2425M9LS250